



Applicant:

Chuen Rong Leu et al.

Assignee:

Bridge Semiconductor Corporation

Title:

METHOD OF MAKING A SEMICONDUCTOR CHIP

ASSEMBLY WITH AN EMBEDDED METAL PILLAR

Serial No.:

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COMMISSIONER FOR PATENTS

P.O. Box 1450

Alexandria, VA 22313-1450

SECOND PRELIMINARY AMENDMENT

Dear Sir:

Please amend the application as follows.

The Specification Amendments begin on page 2.

The Claim Amendments begin on page 4.

The Remarks begin on page 61.

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